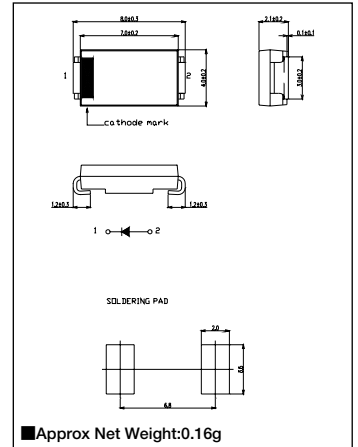


3A Avg. 200 Volts Standard Recovery Diode NSD03A20

最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	V_{RRM}	200	V
平均整流電流 Average Rectified Output Current	I_O	50Hz 正弦半波抵抗負荷 50Hz half sine wave Resistance load	$T_a=25^{\circ}\text{C}^{*1}$ 1.57 A
			$T_l=108^{\circ}\text{C}^{*2}$ 3.0 A
実効順電流 R.M.S. Forward Current	$I_F(\text{RMS})$	4.71	A
サージ順電流 Surge Forward Current	I_{FSM}	80 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	T_{jw}	-40~+150	$^{\circ}\text{C}$
保存温度範囲 Storage Temperature Range	T_{stg}	-40~+150	$^{\circ}\text{C}$

OUTLINE DRAWING(mm)



電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit
ピーク逆電流 Peak Reverse Current	I_{RM}	$T_j=25^{\circ}\text{C}, V_{RM}=V_{RRM}$	—	—	50	μA
ピーク順電圧 Peak Forward Voltage	V_{FM}	$T_j=25^{\circ}\text{C}, I_{FM}=3\text{A}$	—	—	1.0	V
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間*1 Junction to Ambient	—	—	89	$^{\circ}\text{C}/\text{W}$
	$R_{th(j-l)}$	接合部・リード間 Junction to Lead	—	—	13	$^{\circ}\text{C}/\text{W}$

*1: アルミナ基板実装 / Alumina Substrate mounted (Soldering Lands=2×3.5mm, Both Sides)
*2: T_l : リード温度 / T_l : Lead Temperature

定格・特性曲線

FIG.1

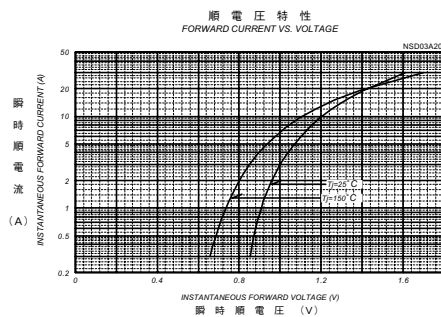


FIG.2

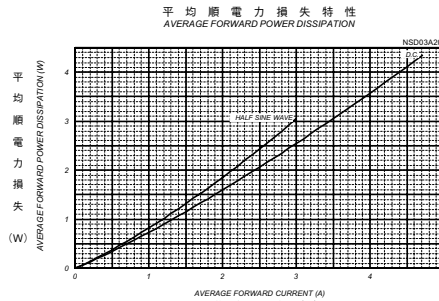


FIG.3

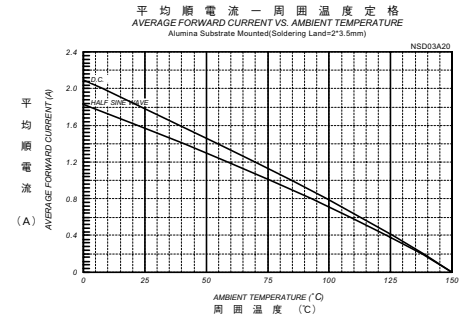


FIG.4

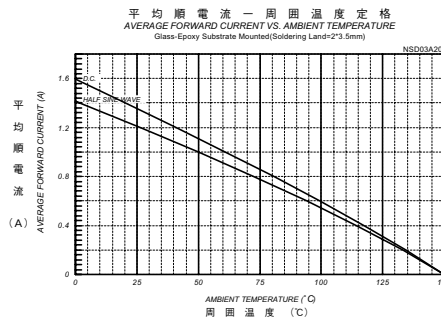


FIG.5

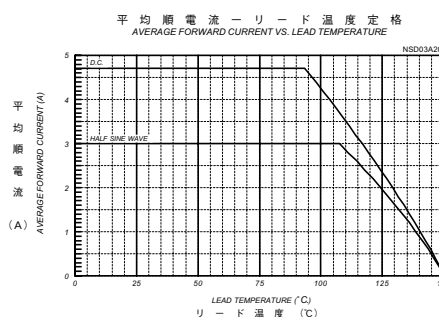


FIG.3

